

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Cheng-Lien Chiang

Assignee:

Bridge Semiconductor Corporation

Title:

METHOD OF MAKING A SEMICONDUCTOR PACKAGE
DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH
RECESSED AND NON-RECESSED PORTIONS

Serial No.:

10/059,686

Filed:

January 29, 2002

Examiner:

Zarneke, D.

Group Art Unit:

2827

Atty. Docket No.:

BDG005-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED

SEP 29 2004

SUPPLEMENTAL RESPONSE

OFFICE OF PETITIONS

Please amend the application as follows.

The Claim Amendments begin at page 2.

The Remarks begin at page 18.